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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	-
Number of Logic Elements/Cells	6100
Total RAM Bits	94208
Number of I/O	147
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	208-BFQFP
Supplier Device Package	208-PQFP (28x28)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfcp6e-3qn208c

Introduction

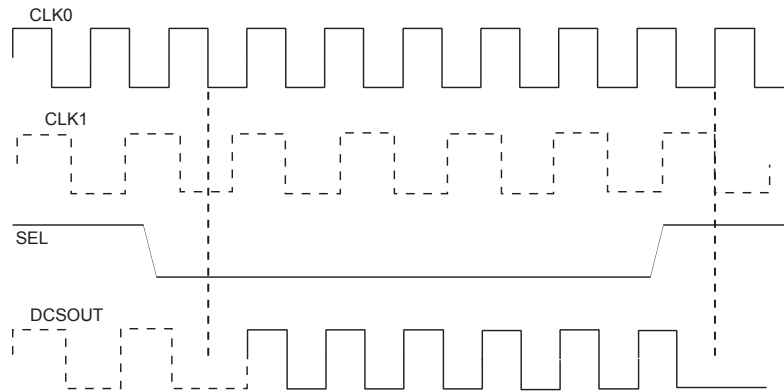
The LatticeECP/EC family of FPGA devices is optimized to deliver mainstream FPGA features at low cost. For maximum performance and value, the LatticeECP™ (Economy Plus) FPGA concept combines an efficient FPGA fabric with high-speed dedicated functions. Lattice's first family to implement this approach is the LatticeECP-DSP™ (Economy Plus DSP) family, providing dedicated high-performance DSP blocks on-chip. The LatticeEC™ (Economy) family supports all the general purpose features of LatticeECP devices without dedicated function blocks to achieve lower cost solutions.

The LatticeECP/EC FPGA fabric, which was designed from the outset with low cost in mind, contains all the critical FPGA elements: LUT-based logic, distributed and embedded memory, PLLs and support for mainstream I/Os. Dedicated DDR memory interface logic is also included to support this memory that is becoming increasingly prevalent in cost-sensitive applications.

The ispLEVER® design tool suite from Lattice allows large complex designs to be efficiently implemented using the LatticeECP/EC FPGA family. Synthesis library support for LatticeECP/EC is available for popular logic synthesis tools. The ispLEVER tool uses the synthesis tool output along with the constraints from its floor planning tools to place and route the design in the LatticeECP/EC device. The ispLEVER tool extracts the timing from the routing and back-annotates it into the design for timing verification.

Lattice provides many pre-designed IP (Intellectual Property) ispLeverCORE™ modules for the LatticeECP/EC family. By using these IPs as standardized blocks, designers are free to concentrate on the unique aspects of their design, increasing their productivity.

Figure 2-14. DCS Waveforms



sysMEM Memory

The LatticeECP/EC devices contain a number of sysMEM Embedded Block RAM (EBR). The EBR consists of a 9-Kbit RAM, with dedicated input and output registers.

sysMEM Memory Block

The sysMEM block can implement single port, dual port or pseudo dual port memories. Each block can be used in a variety of depths and widths as shown in Table 2-6.

Table 2-6. sysMEM Block Configurations

Memory Mode	Configurations
Single Port	8,192 x 1
	4,096 x 2
	2,048 x 4
	1,024 x 9
	512 x 18
	256 x 36
True Dual Port	8,192 x 1
	4,096 x 2
	2,048 x 4
	1,024 x 9
	512 x 18
Pseudo Dual Port	8,192 x 1
	4,096 x 2
	2,048 x 4
	1,024 x 9
	512 x 18
	256 x 36

Bus Size Matching

All of the multi-port memory modes support different widths on each of the ports. The RAM bits are mapped LSB word 0 to MSB word 0, LSB word 1 to MSB word 1 and so on. Although the word size and number of words for each port varies, this mapping scheme applies to each port.

RAM Initialization and ROM Operation

If desired, the contents of the RAM can be pre-loaded during device configuration. By preloading the RAM block during the chip configuration cycle and disabling the write controls, the sysMEM block can also be utilized as a ROM.

Signed and Unsigned with Different Widths

The DSP block supports different widths of signed and unsigned multipliers besides x9, x18 and x36 widths. For unsigned operands, unused upper data bits should be filled to create a valid x9, x18 or x36 operand. For signed two's complement operands, sign extension of the most significant bit should be performed until x9, x18 or x36 width is reached. Table 2-8 provides an example of this.

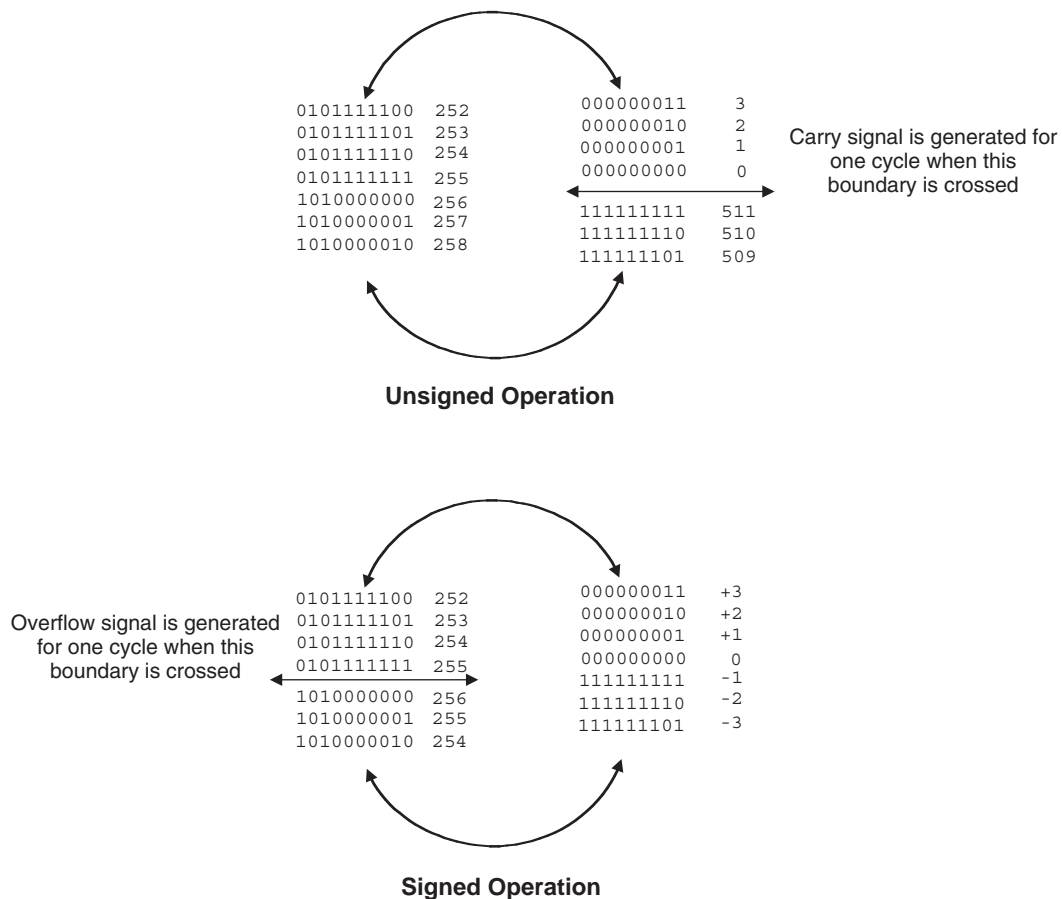
Table 2-8. An Example of Sign Extension

Number	Unsigned	Unsigned 9-bit	Unsigned 18-bit	Signed	Two's Complement Signed 9-Bits	Two's Complement Signed 18-bits
+5	0101	000000101	000000000000000101	0101	000000101	000000000000000101
-6	0110	000000110	000000000000000110	1010	11111010	111111111111111010

OVERFLOW Flag from MAC

The sysDSP block provides an overflow output to indicate that the accumulator has overflowed. When two unsigned numbers are added and the result is a smaller number then accumulator roll over is said to occur and overflow signal is indicated. When two positive numbers are added with a negative sum and when two negative numbers are added with a positive sum, then the accumulator “roll-over” is said to have occurred and an overflow signal is indicated. Note when overflow occurs the overflow flag is present for only one cycle. By counting these overflow pulses in FPGA logic, larger accumulators can be constructed. The conditions overflow signals for signed and unsigned operands are listed in Figure 2-23.

Figure 2-23. Accumulator Overflow/Underflow Conditions



Input Register Block

The input register block contains delay elements and registers that can be used to condition signals before they are passed to the device core. Figure 2-26 shows the diagram of the input register block.

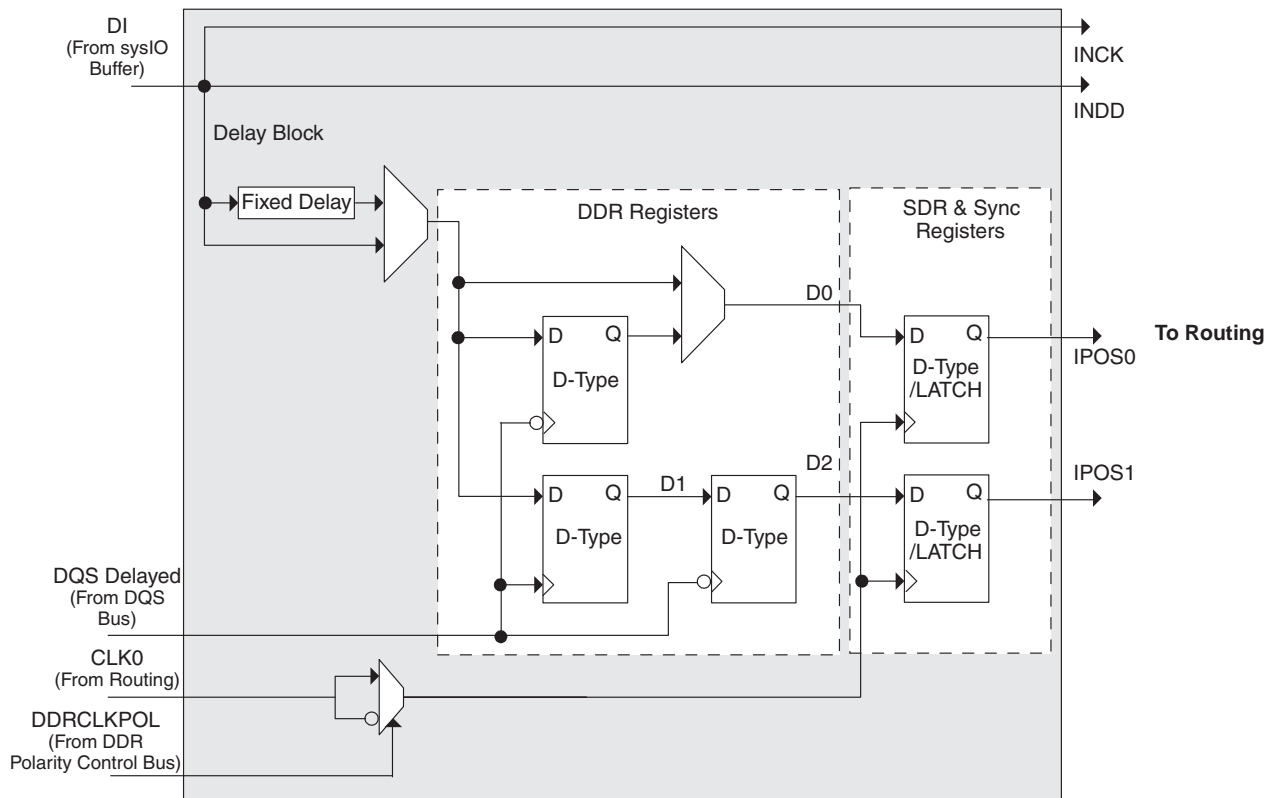
Input signals are fed from the sysI/O buffer to the input register block (as signal DI). If desired the input signal can bypass the register and delay elements and be used directly as a combinatorial signal (INDD), a clock (INCK) and in selected blocks the input to the DQS delay block. If one of the bypass options is not chosen, the signal first passes through an optional delay block. This delay, if selected, reduces input-register hold-time requirement when using a global clock.

The input block allows two modes of operation. In the single data rate (SDR) the data is registered, by one of the registers in the single data rate sync register block, with the system clock. In the DDR Mode two registers are used to sample the data on the positive and negative edges of the DQS signal creating two data streams, D0 and D2. These two data streams are synchronized with the system clock before entering the core. Further discussion on this topic is in the DDR Memory section of this data sheet.

Figure 2-27 shows the input register waveforms for DDR operation and Figure 2-28 shows the design tool primitives. The SDR/SYNC registers have reset and clock enable available.

The signal DDRCLKPOL controls the polarity of the clock used in the synchronization registers. It ensures adequate timing when data is transferred from the DQS to system clock domain. For further discussion on this topic, see the DDR Memory section of this data sheet.

Figure 2-26. Input Register Diagram



Oscillator

Every LatticeECP/EC device has an internal CMOS oscillator which is used to derive a master clock for configuration. The oscillator and the master clock run continuously. The default value of the master clock is 2.5MHz. Table 2-15 lists all the available Master Clock frequencies. When a different Master Clock is selected during the design process, the following sequence takes place:

1. User selects a different Master Clock frequency.
2. During configuration the device starts with the default (2.5MHz) Master Clock frequency.
3. The clock configuration settings are contained in the early configuration bit stream.
4. The Master Clock frequency changes to the selected frequency once the clock configuration bits are received.

For further information about the use of this oscillator for configuration, please see the list of technical documentation at the end of this data sheet.

Table 2-15. Selectable Master Clock (CCLK) Frequencies During Configuration

CCLK (MHz)	CCLK (MHz)	CCLK (MHz)
2.5*	13	45
4.3	15	51
5.4	20	55
6.9	26	60
8.1	30	130
9.2	34	—
10.0	41	—

Density Shifting

The LatticeECP/EC family has been designed to ensure that different density devices in the same package have the same pin-out. Furthermore, the architecture ensures a high success rate when performing design migration from lower density parts to higher density parts. In many cases, it is also possible to shift a lower utilization design targeted for a high-density device to a lower density device. However, the exact details of the final resource utilization will impact the likely success in each case.

Absolute Maximum Ratings^{1, 2, 3}

Supply Voltage V_{CC}	-0.5 to 1.32V
Supply Voltage V_{CCAUX}	-0.5 to 3.75V
Supply Voltage V_{CCJ}	-0.5 to 3.75V
Output Supply Voltage V_{CCIO}	-0.5 to 3.75V
Dedicated Input Voltage Applied ⁴	-0.5 to 4.25V
I/O Tristate Voltage Applied ⁴	-0.5 to 3.75V
Storage Temperature (Ambient)	-65 to 150°C
Junction Temp. (Tj)	+125°C

1. Stress above those listed under the "Absolute Maximum Ratings" may cause permanent damage to the device. Functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.
2. Compliance with the Lattice *Thermal Management* document is required.
3. All voltages referenced to GND.
4. Overshoot and undershoot of -2V to ($V_{IHMAX} + 2$) volts is permitted for a duration of <20ns.

Recommended Operating Conditions

Symbol	Parameter	Min.	Max.	Units
V_{CC}	Core Supply Voltage	1.14	1.26	V
V_{CCAUX}^3	Auxiliary Supply Voltage	3.135	3.465	V
V_{CCPLL}	PLL Supply Voltage for ECP/EC33	1.14	1.26	V
$V_{CCIO}^{1,2}$	I/O Driver Supply Voltage	1.140	3.465	V
V_{CCJ}^1	Supply Voltage for IEEE 1149.1 Test Access Port	1.140	3.465	V
t_{JCOM}	Junction Commercial Operation	0	85	°C
t_{JIND}	Junction Industrial Operation	-40	100	°C

1. If V_{CCIO} or V_{CCJ} is set to 1.2V, they must be connected to the same power supply as V_{CC} . If V_{CCIO} or V_{CCJ} is set to 3.3V, they must be connected to the same power supply as V_{CCAUX} .
2. See recommended voltages by I/O standard in subsequent table.
3. V_{CCAUX} ramp rate must not exceed 3mV/ μ s for commercial and 0.6 mV/ μ s for industrial device operations during power up when transitioning between 0.8V and 1.8V.

Hot Socketing Specifications^{1, 2, 3, 4}

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
Top and Bottom General Purpose sysI/Os (Banks 0, 1, 4 and 5), JTAG and Dedicated sysCONFIG Pins						
I_{DK_TB}	Input or I/O Leakage Current	$0 \delta V_{IN} \delta V_{IH} (MAX.)$	—	—	+/-1000	μ A
Left and Right General Purpose sysI/Os (Banks 2, 3, 6 and 7)						
I_{DK_LR}	Input or I/O Leakage Current	$V_{IN} \delta V_{CCIO}$	—	—	+/-1000	μ A
		$V_{IN} > V_{CCIO}$	—	35	—	mA

1. Insensitive to sequence of V_{CC} , V_{CCAUX} and V_{CCIO} . However, assumes monotonic rise/fall rates for V_{CC} , V_{CCAUX} and V_{CCIO} .
2. $0 \delta V_{CC} \delta V_{CC} (MAX)$, $0 \delta V_{CCIO} \delta V_{CCIO} (MAX)$ or $0 \delta V_{CCAUX} \delta V_{CCAUX} (MAX)$.
3. I_{DK} is additive to I_{PU} , I_{PW} or I_{BH} .
4. LVCMOS and LVTTTL only.

sysI/O Recommended Operating Conditions

Standard	V _{CCIO}			V _{REF} (V)		
	Min.	Typ.	Max.	Min.	Typ.	Max.
LVC MOS 3.3	3.135	3.3	3.465	—	—	—
LVC MOS 2.5	2.375	2.5	2.625	—	—	—
LVC MOS 1.8	1.71	1.8	1.89	—	—	—
LVC MOS 1.5	1.425	1.5	1.575	—	—	—
LVC MOS 1.2	1.14	1.2	1.26	—	—	—
LV TTL	3.135	3.3	3.465	—	—	—
PCI	3.135	3.3	3.465	—	—	—
SSTL18 Class I	1.71	1.8	1.89	0.833	0.90	0.969
SSTL2 Class I, II	2.375	2.5	2.625	1.15	1.25	1.35
SSTL3 Class I, II	3.135	3.3	3.465	1.3	1.5	1.7
HSTL15 Class I	1.425	1.5	1.575	0.68	0.75	0.9
HSTL15 Class III	1.425	1.5	1.575	—	0.9	—
HSTL 18 Class I, II	1.71	1.8	1.89	—	0.9	—
HSTL 18 Class III	1.71	1.8	1.89	—	1.08	—
LVDS	2.375	2.5	2.625	—	—	—
LVPECL ¹	3.135	3.3	3.465	—	—	—
BLVDS ¹	2.375	2.5	2.625	—	—	—
RSDS ¹	2.375	2.5	2.625	—	—	—

1. Outputs are implemented with the addition of external resistors. V_{CCIO} applies to outputs only.

sysI/O Differential Electrical Characteristics

LVDS

Over Recommended Operating Conditions

Parameter Symbol	Parameter Description	Test Conditions	Min.	Typ.	Max.	Units
V_{INP}, V_{INM}	Input voltage		0	—	2.4	V
V_{THD}	Differential input threshold		+/-100	—	—	mV
V_{CM}	Input common mode voltage	100mV δV_{THD}	$V_{THD}/2$	1.2	1.8	V
		200mV δV_{THD}	$V_{THD}/2$	1.2	1.9	V
		350mV δV_{THD}	$V_{THD}/2$	1.2	2.0	V
I_{IN}	Input current	Power on or power off	—	—	+/-10	μ A
V_{OH}	Output high voltage for V_{OP} or V_{OM}	$R_T = 100$ Ohm	—	1.38	1.60	V
V_{OL}	Output low voltage for V_{OP} or V_{OM}	$R_T = 100$ Ohm	0.9V	1.03	—	V
V_{OD}	Output voltage differential	$(V_{OP} - V_{OM}), R_T = 100$ Ohm	250	350	450	mV
ΔV_{OD}	Change in V_{OD} between high and low		—	—	50	mV
V_{OS}	Output voltage offset	$(V_{OP} + V_{OM})/2, R_T = 100$ Ohm	1.125	1.25	1.375	V
ΔV_{OS}	Change in V_{OS} between H and L		—	—	50	mV
I_{OSD}	Output short circuit current	$V_{OD} = 0$ V Driver outputs shorted	—	—	6	mA

Differential HSTL and SSTL

Differential HSTL and SSTL outputs are implemented as a pair of complementary single-ended outputs. All allowable single-ended output classes (class I and class II) are supported in this mode.

LVDS25E

The top and bottom side of LatticeECP/EC devices support LVDS outputs via emulated complementary LVCMOS outputs in conjunction with a parallel resistor across the driver outputs. The scheme shown in

Figure 3-1 is one possible solution for point-to-point signals.

Figure 3-1. LVDS25E Output Termination Example

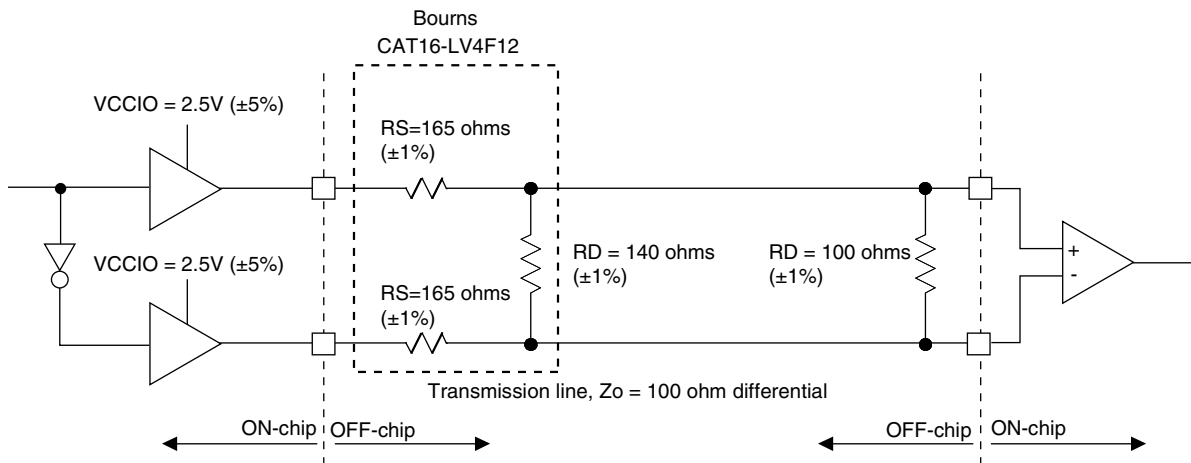


Table 3-1. LVDS25E DC Conditions

Parameter	Description	Typical	Units
V_{OH}	Output high voltage	1.42	V
V_{OL}	Output low voltage	1.08	V
V_{OD}	Output differential voltage	0.35	V
V_{CM}	Output common mode voltage	1.25	V
Z_{BACK}	Back impedance	100	$\%$

LatticeECP/EC Family Timing Adders^{1, 2, 3}
Over Recommended Operating Conditions

Buffer Type	Description	-5	-4	-3	Units
Input Adjusters					
LVDS25	LVDS	0.41	0.50	0.58	ns
BLVDS25	BLVDS	0.41	0.50	0.58	ns
LVPECL33	LVPECL	0.50	0.60	0.70	ns
HSTL18_I	HSTL_18 class I	0.41	0.49	0.57	ns
HSTL18_II	HSTL_18 class II	0.41	0.49	0.57	ns
HSTL18_III	HSTL_18 class III	0.41	0.49	0.57	ns
HSTL18D_I	Differential HSTL 18 class I	0.37	0.44	0.52	ns
HSTL18D_II	Differential HSTL 18 class II	0.37	0.44	0.52	ns
HSTL18D_III	Differential HSTL 18 class III	0.37	0.44	0.52	ns
HSTL15_I	HSTL_15 class I	0.40	0.48	0.56	ns
HSTL15_III	HSTL_15 class III	0.40	0.48	0.56	ns
HSTL15D_I	Differential HSTL 15 class I	0.37	0.44	0.51	ns
HSTL15D_III	Differential HSTL 15 class III	0.37	0.44	0.51	ns
SSTL33_I	SSTL_3 class I	0.46	0.55	0.64	ns
SSTL33_II	SSTL_3 class II	0.46	0.55	0.64	ns
SSTL33D_I	Differential SSTL_3 class I	0.39	0.47	0.55	ns
SSTL33D_II	Differential SSTL_3 class II	0.39	0.47	0.55	ns
SSTL25_I	SSTL_2 class I	0.43	0.51	0.60	ns
SSTL25_II	SSTL_2 class II	0.43	0.51	0.60	ns
SSTL25D_I	Differential SSTL_2 class I	0.38	0.45	0.53	ns
SSTL25D_II	Differential SSTL_2 class II	0.38	0.45	0.53	ns
SSTL18_I	SSTL_18 class I	0.40	0.48	0.56	ns
SSTL18D_I	Differential SSTL_18 class I	0.37	0.44	0.51	ns
LVTTTL33	LVTTTL	0.07	0.09	0.10	ns
LVC MOS33	LVC MOS 3.3	0.07	0.09	0.10	ns
LVC MOS25	LVC MOS 2.5	0.00	0.00	0.00	ns
LVC MOS18	LVC MOS 1.8	0.07	0.09	0.10	ns
LVC MOS15	LVC MOS 1.5	0.24	0.29	0.33	ns
LVC MOS12	LVC MOS 1.2	1.27	1.52	1.77	ns
PCI33	PCI	0.07	0.09	0.10	ns
Output Adjusters					
LVDS25E	LVDS 2.5 E	0.12	0.14	0.17	ns
LVDS25	LVDS 2.5	-0.44	-0.53	-0.62	ns
BLVDS25	BLVDS 2.5	0.33	0.40	0.46	ns
LVPECL33	LVPECL 3.3	0.20	0.24	0.28	ns
HSTL18_I	HSTL_18 class I	-0.10	-0.12	-0.14	ns
HSTL18_II	HSTL_18 class II	0.06	0.07	0.08	ns
HSTL18_III	HSTL_18 class III	0.15	0.19	0.22	ns
HSTL18D_I	Differential HSTL 18 class I	-0.10	-0.12	-0.14	ns
HSTL18D_II	Differential HSTL 18 class II	0.06	0.07	0.08	ns
HSTL18D_III	Differential HSTL 18 class III	0.15	0.19	0.22	ns
HSTL15_I	HSTL_15 class I	0.08	0.10	0.11	ns

LatticeECP/EC Family Timing Adders^{1, 2, 3} (Continued)
Over Recommended Operating Conditions

Buffer Type	Description	-5	-4	-3	Units
HSTL15_II	HSTL_15 class II	0.10	0.12	0.14	ns
HSTL15_III	HSTL_15 class III	0.10	0.12	0.14	ns
HSTL15D_I	Differential HSTL 15 class I	0.08	0.10	0.11	ns
HSTL15D_III	Differential HSTL 15 class III	0.10	0.12	0.14	ns
SSTL33_I	SSTL_3 class I	-0.05	-0.06	-0.07	ns
SSTL33_II	SSTL_3 class II	0.40	0.48	0.56	ns
SSTL33D_I	Differential SSTL_3 class I	-0.05	-0.06	-0.07	ns
SSTL33D_II	Differential SSTL_3 class II	0.40	0.48	0.56	ns
SSTL25_I	SSTL_2 class I	0.05	0.07	0.08	ns
SSTL25_II	SSTL_2 class II	0.25	0.30	0.35	ns
SSTL25D_I	Differential SSTL_2 class I	0.05	0.07	0.08	ns
SSTL25D_II	Differential SSTL_2 class II	0.25	0.30	0.35	ns
SSTL18_I	SSTL_1.8 class I	0.01	0.01	0.01	ns
SSTL18D_I	Differential SSTL_1.8 class I	0.01	0.01	0.01	ns
LVTTTL33_4mA	LVTTTL 4mA drive	0.09	0.11	0.13	ns
LVTTTL33_8mA	LVTTTL 8mA drive	0.07	0.08	0.09	ns
LVTTTL33_12mA	LVTTTL 12mA drive	-0.03	-0.04	-0.05	ns
LVTTTL33_16mA	LVTTTL 16mA drive	0.36	0.43	0.51	ns
LVTTTL33_20mA	LVTTTL 20mA drive	0.28	0.33	0.39	ns
LVC MOS33_4mA	LVC MOS 3.3 4mA drive	0.09	0.11	0.13	ns
LVC MOS33_8mA	LVC MOS 3.3 8mA drive	0.07	0.08	0.09	ns
LVC MOS33_12mA	LVC MOS 3.3 12mA drive	-0.03	-0.04	-0.05	ns
LVC MOS33_16mA	LVC MOS 3.3 16mA drive	0.36	0.43	0.51	ns
LVC MOS33_20mA	LVC MOS 3.3 20mA drive	0.28	0.33	0.39	ns
LVC MOS25_4mA	LVC MOS 2.5 4mA drive	0.18	0.21	0.25	ns
LVC MOS25_8mA	LVC MOS 2.5 8mA drive	0.10	0.12	0.14	ns
LVC MOS25_12mA	LVC MOS 2.5 12mA drive	0.00	0.00	0.00	ns
LVC MOS25_16mA	LVC MOS 2.5 16mA drive	0.22	0.26	0.31	ns
LVC MOS25_20mA	LVC MOS 2.5 20mA drive	0.14	0.16	0.19	ns
LVC MOS18_4mA	LVC MOS 1.8 4mA drive	0.15	0.18	0.21	ns
LVC MOS18_8mA	LVC MOS 1.8 8mA drive	0.06	0.08	0.09	ns
LVC MOS18_12mA	LVC MOS 1.8 12mA drive	0.01	0.01	0.01	ns
LVC MOS18_16mA	LVC MOS 1.8 16mA drive	0.16	0.19	0.22	ns
LVC MOS15_4mA	LVC MOS 1.5 4mA drive	0.26	0.31	0.36	ns
LVC MOS15_8mA	LVC MOS 1.5 8mA drive	0.04	0.04	0.05	ns
LVC MOS12_2mA	LVC MOS 1.2 2mA drive	0.36	0.43	0.50	ns
LVC MOS12_6mA	LVC MOS 1.2 6mA drive	0.08	0.10	0.11	ns
LVC MOS12_4mA	LVC MOS 1.2 4mA drive	0.36	0.43	0.50	ns
PCI33	PCI33	1.05	1.26	1.46	ns

1. Timing adders are characterized but not tested on every device.

2. LVC MOS timing measured with the load specified in Switching Test Conditions table of this document.

3. All other standards according to the appropriate specification.

Timing v.G 0.30

LFEC1, LFEC3 Logic Signal Connections: 208 PQFP (Cont.)

Pin Number	LFEC1				LFEC3			
	Pin Function	Bank	LVDS	Dual Function	Pin Function	Bank	LVDS	Dual Function
85	VCCIO4	4			VCCIO4	4		
86	PB10A	4	T	WRITEN	PB18A	4	T	WRITEN
87	PB10B	4	C	CS1N	PB18B	4	C	CS1N
88	PB11A	4	T	VREF1_4	PB19A	4	T	VREF1_4
89	PB11B	4	C	CSN	PB19B	4	C	CSN
90	PB12A	4	T	VREF2_4	PB20A	4	T	VREF2_4
91	PB12B	4	C	D0/SPID7	PB20B	4	C	D0/SPID7
92	PB13A	4	T	D2/SPID5	PB21A	4	T	D2/SPID5
93	GND4	4			GND4	4		
94	PB13B	4	C	D1/SPID6	PB21B	4	C	D1/SPID6
95	PB14A	4	T	BDQS14	PB22A	4	T	BDQS22
96	PB14B	4	C	D3/SPID4	PB22B	4	C	D3/SPID4
97	PB15A	4	T		PB23A	4	T	
98	PB15B	4	C	D4/SPID3	PB23B	4	C	D4/SPID3
99	PB16A	4	T		PB24A	4	T	
100	PB16B	4	C	D5/SPID2	PB24B	4	C	D5/SPID2
101	PB17A	4	T		PB25A	4	T	
102	PB17B	4	C	D6/SPID1	PB25B	4	C	D6/SPID1
103	NC	-			NC	-		
104	VCCIO4	4			VCCIO4	4		
105*	GND3 GND4	-			GND3 GND4	-		
106	VCCIO3	3			VCCIO3	3		
107	PR14B	3	C	VREF2_3	PR18B	3	C	VREF2_3
108	PR14A	3	T	VREF1_3	PR18A	3	T	VREF1_3
109	PR13B	3	C		PR17B	3	C	
110	PR13A	3	T		PR17A	3	T	
111	PR12B	3	C		PR16B	3	C	
112	PR12A	3	T		PR16A	3	T	
113	PR11B	3	C		PR15B	3	C	
114	PR11A	3	T	RDQS11	PR15A	3	T	RDQS15
115	PR10B	3	C	RLM0_PLLC_FB_A	PR14B	3	C	RLM0_PLLC_FB_A
116	GND3	3			GND3	3		
117	PR10A	3	T	RLM0_PLLT_FB_A	PR14A	3	T	RLM0_PLLT_FB_A
118	PR9B	3	C	RLM0_PLLC_IN_A	PR13B	3	C	RLM0_PLLC_IN_A
119	PR9A	3	T	RLM0_PLLT_IN_A	PR13A	3	T	RLM0_PLLT_IN_A
120	VCCIO3	3			VCCIO3	3		
121	PR8B	3	C	DI/CSSPIN	PR12B	3	C	DI/CSSPIN
122	PR8A	3	T	DOUT/CSON	PR12A	3	T	DOUT/CSON
123	PR7B	3	C	BUSY/SISPI	PR11B	3	C	BUSY/SISPI
124	PR7A	3	T	D7/SPID0	PR11A	3	T	D7/SPID0
125	CFG2	3			CFG2	3		
126	CFG1	3			CFG1	3		

LFECP/EC10 and LFECP/EC15 Logic Signal Connections: 256 fpBGA (Cont.)

Ball Number	LFECP10/LFEC10				LFECP15/LFEC15			
	Ball Function	Bank	LVDS	Dual Function	Ball Function	Bank	LVDS	Dual Function
N7	PB18B	5	C		PB18B	5	C	
R7	PB19A	5	T		PB19A	5	T	
R8	PB19B	5	C		PB19B	5	C	
M7	PB20A	5	T		PB20A	5	T	
M8	PB20B	5	C		PB20B	5	C	
T8	PB21A	5	T		PB21A	5	T	
GND	GND5	5			GND5	5		
T9	PB21B	5	C		PB21B	5	C	
P8	PB22A	5	T	BDQS22	PB22A	5	T	BDQS22
N8	PB22B	5	C		PB22B	5	C	
R9	PB23A	5	T		PB23A	5	T	
R10	PB23B	5	C		PB23B	5	C	
P9	PB24A	5	T	VREF2_5	PB24A	5	T	VREF2_5
N9	PB24B	5	C	VREF1_5	PB24B	5	C	VREF1_5
T10	PB25A	5	T	PCLKT5_0	PB25A	5	T	PCLKT5_0
GND	GND5	5			GND5	5		
T11	PB25B	5	C	PCLKC5_0	PB25B	5	C	PCLKC5_0
T12	PB26A	4	T	WRITEN	PB26A	4	T	WRITEN
T13	PB26B	4	C	CS1N	PB26B	4	C	CS1N
P10	PB27A	4	T	VREF1_4	PB27A	4	T	VREF1_4
N10	PB27B	4	C	CSN	PB27B	4	C	CSN
T14	PB28A	4	T	VREF2_4	PB28A	4	T	VREF2_4
T15	PB28B	4	C	D0/SPID7	PB28B	4	C	D0/SPID7
M10	PB29A	4	T	D2/SPID5	PB29A	4	T	D2/SPID5
GND	GND4	4			GND4	4		
M11	PB29B	4	C	D1/SPID6	PB29B	4	C	D1/SPID6
R11	PB30A	4	T	BDQS30	PB30A	4	T	BDQS30
P11	PB30B	4	C	D3/SPID4	PB30B	4	C	D3/SPID4
R13	PB31A	4	T		PB31A	4	T	
R14	PB31B	4	C	D4/SPID3	PB31B	4	C	D4/SPID3
P12	PB32A	4	T		PB32A	4	T	
P13	PB32B	4	C	D5/SPID2	PB32B	4	C	D5/SPID2
N11	PB33A	4	T		PB33A	4	T	
GND	GND4	4			GND4	4		
N12	PB33B	4	C	D6/SPID1	PB33B	4	C	D6/SPID1
R12	PB34A	4			PB34A	4		
GND	GND4	4			GND4	4		
GND	GND4	4			GND4	4		
-	-	-			GND4	4		
-	-	-			GND4	4		
GND	GND3	3			GND3	3		
N13	PR36B	3	C	VREF2_3	PR44B	3	C	VREF2_3
N14	PR36A	3	T	VREF1_3	PR44A	3	T	VREF1_3

**LFECP/EC6, LFECP/EC10, LFECP/EC15 Logic Signal Connections:
 484 fpBGA (Cont.)**

LFECP6/LFEC6					LFECP10/LFEC10					LFECP/LFEC15				
Ball Number	Ball Function	Bank	LVDS	Dual Function	Ball Number	Ball Function	Bank	LVDS	Dual Function	Ball Number	Ball Function	Bank	LVDS	Dual Function
C21	NC	-			C21	PR5B	2	C		C21	PR5B	2	C	
C20	NC	-			C20	PR5A	2	T		C20	PR5A	2	T	
F18	NC	-			F18	PR4B	2	C		F18	PR4B	2	C	
E18	NC	-			E18	PR4A	2	T		E18	PR4A	2	T	
B22	NC	-			B22	PR3B	2	C		B22	PR3B	2	C	
B21	NC	-			B21	PR3A	2	T		B21	PR3A	2	T	
E19	PR2B	2	C	VREF1_2	E19	PR2B	2	C	VREF1_2	E19	PR2B	2	C	VREF1_2
D19	PR2A	2	T	VREF2_2	D19	PR2A	2	T	VREF2_2	D19	PR2A	2	T	VREF2_2
GND	GND2	2			GND	GND2	2			GND	GND2	2		
GND	GND1	1			GND	GND1	1			GND	GND1	1		
G17	NC	-			G17	NC	-			G17	PT49B	1	C	
F17	NC	-			F17	NC	-			F17	PT49A	1	T	
D18	NC	-			D18	NC	-			D18	PT48B	1	C	
C18	NC	-			C18	NC	-			C18	PT48A	1	T	
C19	NC	-			C19	NC	-			C19	PT47B	1	C	
B20	NC	-			B20	NC	-			B20	PT47A	1	T	
D17	NC	-			D17	NC	-			D17	PT46B	1	C	
C16	NC	-			C16	NC	-			C16	PT46A	1	T	TDQS46
B19	NC	-			B19	NC	-			B19	PT45B	1	C	
GND	-	-			GND	-	-			GND	GND1	1		
A20	NC	-			A20	NC	-			A20	PT45A	1	T	
E17	NC	-			E17	NC	-			E17	PT44B	1	C	
C17	NC	-			C17	NC	-			C17	PT44A	1	T	
F16	NC	-			F16	NC	-			F16	PT43B	1	C	
E16	NC	-			E16	NC	-			E16	PT43A	1	T	
F15	NC	-			F15	NC	-			F15	PT42B	1	C	
D16	NC	-			D16	NC	-			D16	PT42A	1	T	
B18	PT33B	1	C		B18	PT41B	1	C		B18	PT41B	1	C	
GND	-	-			GND	-	-			GND	GND1	1		
A19	PT33A	1	T		A19	PT41A	1	T		A19	PT41A	1	T	
B17	PT32B	1	C		B17	PT40B	1	C		B17	PT40B	1	C	
A18	PT32A	1	T		A18	PT40A	1	T		A18	PT40A	1	T	
B16	PT31B	1	C		B16	PT39B	1	C		B16	PT39B	1	C	
A17	PT31A	1	T		A17	PT39A	1	T		A17	PT39A	1	T	
B15	PT30B	1	C		B15	PT38B	1	C		B15	PT38B	1	C	
A16	PT30A	1	T	TDQS30	A16	PT38A	1	T	TDQS38	A16	PT38A	1	T	TDQS38
A15	PT29B	1	C		A15	PT37B	1	C		A15	PT37B	1	C	
GND	GND1	1			GND	GND1	1			GND	GND1	1		
A14	PT29A	1	T		A14	PT37A	1	T		A14	PT37A	1	T	
G14	PT28B	1	C		G14	PT36B	1	C		G14	PT36B	1	C	
E15	PT28A	1	T		E15	PT36A	1	T		E15	PT36A	1	T	
D15	PT27B	1	C		D15	PT35B	1	C		D15	PT35B	1	C	
C15	PT27A	1	T		C15	PT35A	1	T		C15	PT35A	1	T	
C14	PT26B	1	C		C14	PT34B	1	C		C14	PT34B	1	C	
B14	PT26A	1	T		B14	PT34A	1	T		B14	PT34A	1	T	
A13	PT25B	1	C		A13	PT33B	1	C		A13	PT33B	1	C	
GND	GND1	1			GND	GND1	1			GND	GND1	1		
B13	PT25A	1	T		B13	PT33A	1	T		B13	PT33A	1	T	
E14	PT24B	1	C		E14	PT32B	1	C		E14	PT32B	1	C	
C13	PT24A	1	T		C13	PT32A	1	T		C13	PT32A	1	T	

LFECP/EC20 and LFECP/EC33 Logic Signal Connections: 484 fpBGA

LFECP20/LFEC20					LFECP/LFEC33				
Ball Number	Ball Function	Bank	LVD S	Dual Function	Ball Number	Ball Function	Bank	LVD S	Dual Function
GND	GND7	7			GND	GND7	7		
D4	PL2A	7	T	VREF2_7	D4	PL2A	7	T	VREF2_7
E4	PL2B	7	C	VREF1_7	E4	PL2B	7	C	VREF1_7
GND	-	-			GND	GND7	7		
C3	PL3A	7	T		C3	PL10A	7	T	
B2	PL3B	7	C		B2	PL10B	7	C	
E5	PL4A	7	T		E5	PL11A	7	T	
F5	PL4B	7	C		F5	PL11B	7	C	
D3	PL5A	7	T		D3	PL12A	7	T	
C2	PL5B	7	C		C2	PL12B	7	C	
GND	-	-			GND	GND7	7		
F4	PL6A	7	T	LDQS6	F4	PL14A	7	T	LDQS14
G4	PL6B	7	C		G4	PL14B	7	C	
E3	PL7A	7	T		E3	PL15A	7	T	
D2	PL7B	7	C		D2	PL15B	7	C	
B1	PL8A	7	T	LUM0_PLLT_IN_A	B1	PL16A	7	T	LUM0_PLLT_IN_A
C1	PL8B	7	C	LUM0_PLLC_IN_A	C1	PL16B	7	C	LUM0_PLLC_IN_A
F3	PL9A	7	T	LUM0_PLLT_FB_A	F3	PL17A	7	T	LUM0_PLLT_FB_A
GND	GND7	7			GND	GND7	7		
E2	PL9B	7	C	LUM0_PLLC_FB_A	E2	PL17B	7	C	LUM0_PLLC_FB_A
GND	-	-			GND	GND7	7		
G5	PL11A	7	T		G5	PL23A	7	T	LDQS23
H6	PL11B	7	C		H6	PL23B	7	C	
G3	PL12A	7	T		G3	PL24A	7	T	
H4	PL12B	7	C		H4	PL24B	7	C	
J5	PL13A	7	T		J5	PL25A	7	T	
H5	PL13B	7	C		H5	PL25B	7	C	
F2	PL14A	7	T		F2	PL26A	7	T	
GND	GND7	7			GND	GND7	7		
F1	PL14B	7	C		F1	PL26B	7	C	
E1	PL15A	7	T		E1	PL27A	7	T	
D1	PL15B	7	C		D1	PL27B	7	C	
H3	PL16A	7	T		H3	PL28A	7	T	
G2	PL16B	7	C		G2	PL28B	7	C	
H2	PL17A	7	T		H2	PL29A	7	T	
G1	PL17B	7	C		G1	PL29B	7	C	
J4	PL18A	7	T		J4	PL30A	7	T	
GND	GND7	7			GND	GND7	7		
J3	PL18B	7	C		J3	PL30B	7	C	
J2	PL19A	7	T	LDQS19	J2	PL31A	7	T	LDQS31
H1	PL19B	7	C		H1	PL31B	7	C	
K4	PL20A	7	T		K4	PL32A	7	T	
K5	PL20B	7	C		K5	PL32B	7	C	

LFECP/EC20 and LFECP/EC33 Logic Signal Connections: 484 fpBGA (Cont.)

LFECP20/LFEC20					LFECP/LFEC33				
Ball Number	Ball Function	Bank	LVD S	Dual Function	Ball Number	Ball Function	Bank	LVD S	Dual Function
N22	PR30A	3	T		N22	PR42A	3	T	
N19	PR29B	3	C		N19	PR41B	3	C	
N18	PR29A	3	T		N18	PR41A	3	T	
M21	PR28B	3	C		M21	PR40B	3	C	
L20	PR28A	3	T	RDQS28	L20	PR40A	3	T	RDQS40
L21	PR27B	3	C		L21	PR39B	3	C	
GND	GND3	3			GND	GND3	3		
M20	PR27A	3	T		M20	PR39A	3	T	
M18	PR26B	3	C		M18	PR38B	3	C	
M19	PR26A	3	T		M19	PR38A	3	T	
M22	PR25B	3	C		M22	PR37B	3	C	
L22	PR25A	3	T		L22	PR37A	3	T	
K22	PR24B	3	C		K22	PR36B	3	C	
K21	PR24A	3	T		K21	PR36A	3	T	
J22	PR22B	2	C	PCLKC2_0	J22	PR34B	2	C	PCLKC2_0
GND	GND2	2			GND	GND2	2		
J21	PR22A	2	T	PCLKT2_0	J21	PR34A	2	T	PCLKT2_0
H22	PR21B	2	C		H22	PR33B	2	C	
H21	PR21A	2	T		H21	PR33A	2	T	
L19	PR20B	2	C		L19	PR32B	2	C	
L18	PR20A	2	T		L18	PR32A	2	T	
K20	PR19B	2	C		K20	PR31B	2	C	
J20	PR19A	2	T	RDQS19	J20	PR31A	2	T	RDQS31
K19	PR18B	2	C		K19	PR30B	2	C	
GND	GND2	2			GND	GND2	2		
K18	PR18A	2	T		K18	PR30A	2	T	
G22	PR17B	2	C		G22	PR29B	2	C	
F22	PR17A	2	T		F22	PR29A	2	T	
F21	PR16B	2	C		F21	PR28B	2	C	
E22	PR16A	2	T		E22	PR28A	2	T	
E21	PR15B	2	C		E21	PR27B	2	C	
D22	PR15A	2	T		D22	PR27A	2	T	
G21	PR14B	2	C		G21	PR26B	2	C	
G20	PR14A	2	T		G20	PR26A	2	T	
GND	GND2	2			GND	GND2	2		
J18	PR13B	2	C		J18	PR25B	2	C	
H19	PR13A	2	T		H19	PR25A	2	T	
J19	PR12B	2	C		J19	PR24B	2	C	
H20	PR12A	2	T		H20	PR24A	2	T	
H17	PR11B	2	C		H17	PR23B	2	C	
H18	PR11A	2	T		H18	PR23A	2	T	RDQS23
D21	PR9B	2	C	RUM0_PLLC_FB_A	D21	PR17B	2	C	RUM0_PLLC_FB_A
GND	GND2	2			GND	GND2	2		
GND	-	-			GND	GND2	2		

LFCEP/EC20, LFCEP/EC33 Logic Signal Connections: 672 fpBGA (Cont.)

LFCEP/EC20					LFCEP/EC33				
Ball Number	Ball Function	Bank	LVDS	Dual Function	Ball Number	Ball Function	Bank	LVDS	Dual Function
AF22	PB51A	4	T		AF22	PB51A	4	T	
AB17	PB51B	4	C		AB17	PB51B	4	C	
AE22	PB52A	4	T		AE22	PB52A	4	T	
AA18	PB52B	4	C		AA18	PB52B	4	C	
AE19	PB53A	4	T		AE19	PB53A	4	T	
GND	GND4	4			GND	GND4	4		
AE20	PB53B	4	C		AE20	PB53B	4	C	
AA19	PB54A	4	T	BDQS54	AA19	PB54A	4	T	BDQS54
Y18	PB54B	4	C		Y18	PB54B	4	C	
AF23	PB55A	4	T		AF23	PB55A	4	T	
AA20	PB55B	4	C		AA20	PB55B	4	C	
AC18	PB56A	4	T		AC18	PB56A	4	T	
AB18	PB56B	4	C		AB18	PB56B	4	C	
AF24	PB57A	4	T		AF24	PB57A	4	T	
-	-	-			GND	GND4	4		
AE23	PB57B	4	C		AE23	PB57B	4	C	
AD19	NC	-			AD19	PB58A	4	T	
AD20	NC	-			AD20	PB58B	4	C	
AC19	NC	-			AC19	PB59A	4	T	
AB19	NC	-			AB19	PB59B	4	C	
AD21	NC	-			AD21	PB60A	4	T	
AC20	NC	-			AC20	PB60B	4	C	
AF25	NC	-			AF25	PB61A	4	T	
-	-	-			GND	GND4	4		
AE25	NC	-			AE25	PB61B	4	C	
AB21	NC	-			AB21	PB62A	4	T	BDQS62
AB20	NC	-			AB20	PB62B	4	C	
AE24	NC	-			AE24	PB63A	4	T	
AD23	NC	-			AD23	PB63B	4	C	
AD22	NC	-			AD22	PB64A	4	T	
AC21	NC	-			AC21	PB64B	4	C	
AC22	NC	-			AC22	PB65A	4	T	
AB22	NC	-			AB22	PB65B	4	C	
GND	GND4	4			GND	GND4	4		
GND	GND3	3			GND	GND3	3		
AC23	PR48B	3	C	VREF2_3	AC23	PR68B	3	C	VREF2_3
AC24	PR48A	3	T	VREF1_3	AC24	PR68A	3	T	VREF1_3
AD24	NC	-			AD24	PR67B	3	C	
AD25	NC	-			AD25	PR67A	3	T	
AE26	NC	-			AE26	PR66B	3	C	
AD26	NC	-			AD26	PR66A	3	T	
Y20	NC	-			Y20	PR65B	3	C	

LFCEP/EC20, LFCEP/EC33 Logic Signal Connections: 672 fpBGA (Cont.)

LFCEP/EC20					LFCEP/EC33				
Ball Number	Ball Function	Bank	LVDS	Dual Function	Ball Number	Ball Function	Bank	LVDS	Dual Function
Y19	NC	-			Y19	PR65A	3	T	RDQS65
AA23	NC	-			AA23	PR64B	3	C	
-	-	-			GND	GND3	3		
AA22	NC	-			AA22	PR64A	3	T	
AB23	NC	-			AB23	PR63B	3	C	
AB24	NC	-			AB24	PR63A	3	T	
Y21	NC	-			Y21	PR62B	3	C	
AA21	NC	-			AA21	PR62A	3	T	
Y23	NC	-			Y23	PR61B	3	C	
Y22	NC	-			Y22	PR61A	3	T	
AA24	NC	-			AA24	PR60B	3	C	
-	-	-			GND	GND3	3		
Y24	NC	-			Y24	PR60A	3	T	
AC25	PR47B	3	C		AC25	PR59B	3	C	
AC26	PR47A	3	T		AC26	PR59A	3	T	
AB25	PR46B	3	C		AB25	PR58B	3	C	
AA25	PR46A	3	T		AA25	PR58A	3	T	
AB26	PR45B	3	C		AB26	PR57B	3	C	
AA26	PR45A	3	T	RDQS45	AA26	PR57A	3	T	RDQS57
W23	PR44B	3	C	RLM0_PLLC_IN_A	W23	PR56B	3	C	RLM0_PLLC_IN_A
GND	GND3	3			GND	GND3	3		
W24	PR44A	3	T	RLM0_PLLT_IN_A	W24	PR56A	3	T	RLM0_PLLT_IN_A
W22	PR43B	3	C	RLM0_PLLC_FB_A	W22	PR55B	3	C	RLM0_PLLC_FB_A
W21	PR43A	3	T	RLM0_PLLT_FB_A	W21	PR55A	3	T	RLM0_PLLT_FB_A
Y25	PR42B	3	C	DI/CSSPIN	Y25	PR54B	3	C	DI/CSSPIN
Y26	PR42A	3	T	DOUT/CSON	Y26	PR54A	3	T	DOUT/CSON
W25	PR41B	3	C	BUSY/SISPI	W25	PR53B	3	C	BUSY/SISPI
W26	PR41A	3	T	D7/SPID0	W26	PR53A	3	T	D7/SPID0
V24	CFG2	3			V24	CFG2	3		
V21	CFG1	3			V21	CFG1	3		
V23	CFG0	3			V23	CFG0	3		
V22	PROGRAMN	3			V22	PROGRAMN	3		
V20	CCLK	3			V20	CCLK	3		
V25	INITN	3			V25	INITN	3		
U20	DONE	3			U20	DONE	3		
V26	PR39B	3	C		V26	PR51B	3	C	
GND	GND3	3			GND	GND3	3		
U26	PR39A	3	T		U26	PR51A	3	T	
U24	PR38B	3	C		U24	PR50B	3	C	
U25	PR38A	3	T		U25	PR50A	3	T	
U23	PR37B	3	C		U23	PR49B	3	C	
U22	PR37A	3	T		U22	PR49A	3	T	

LFCEP/EC20, LFCEP/EC33 Logic Signal Connections: 672 fpBGA (Cont.)

LFCEP/EC20					LFCEP/EC33				
Ball Number	Ball Function	Bank	LVDS	Dual Function	Ball Number	Ball Function	Bank	LVDS	Dual Function
M10	GND	-			M10	GND	-		
M11	GND	-			M11	GND	-		
M12	GND	-			M12	GND	-		
M13	GND	-			M13	GND	-		
M14	GND	-			M14	GND	-		
M15	GND	-			M15	GND	-		
M16	GND	-			M16	GND	-		
M17	GND	-			M17	GND	-		
N10	GND	-			N10	GND	-		
N11	GND	-			N11	GND	-		
N12	GND	-			N12	GND	-		
N13	GND	-			N13	GND	-		
N14	GND	-			N14	GND	-		
N15	GND	-			N15	GND	-		
N16	GND	-			N16	GND	-		
N17	GND	-			N17	GND	-		
P10	GND	-			P10	GND	-		
P11	GND	-			P11	GND	-		
P12	GND	-			P12	GND	-		
P13	GND	-			P13	GND	-		
P14	GND	-			P14	GND	-		
P15	GND	-			P15	GND	-		
P16	GND	-			P16	GND	-		
P17	GND	-			P17	GND	-		
R10	GND	-			R10	GND	-		
R11	GND	-			R11	GND	-		
R12	GND	-			R12	GND	-		
R13	GND	-			R13	GND	-		
R14	GND	-			R14	GND	-		
R15	GND	-			R15	GND	-		
R16	GND	-			R16	GND	-		
R17	GND	-			R17	GND	-		
T10	GND	-			T10	GND	-		
T11	GND	-			T11	GND	-		
T12	GND	-			T12	GND	-		
T13	GND	-			T13	GND	-		
T14	GND	-			T14	GND	-		
T15	GND	-			T15	GND	-		
T16	GND	-			T16	GND	-		
T17	GND	-			T17	GND	-		
U10	GND	-			U10	GND	-		
U11	GND	-			U11	GND	-		

Date	Version	Section	Change Summary
September 2005	02.0	Architecture	sysIO section has been updated.
		DC & Switching Characteristics	Recommended Operating Conditions has been updated with V_{CCPLL} .
			DC Electrical Characteristics table has been updated
			Removed 5V Tolerant Input Buffer section.
			Register-to-Register performance table has been updated (rev. G 0.28).
			LatticeECP/EC External Switching Characteristics table has been updated (rev. G 0.28).
			LatticeECP/EC Internal Switching Characteristics table has been updated (rev. G 0.28).
			LatticeECP/EC Family Timing Adders have been updated (rev. G 0.28).
			sysCLOCK PLL timing table has been updated (rev. G 0.28)
			LatticeECP/EC sysCONFIG Port Timing specification table has been updated (rev. G 0.28).
			Master Clock table has been updated (rev. G 0.28).
JTAG Port Timing specification table has been updated (rev. G 0.28).			
Pinout Information	Signal Description table has been updated with V_{CCPLL} .		
November 2005	02.1	DC & Switching Characteristics	Pin-to-Pin Performance table has been updated (G 0.30) - 4:1MUX, 8:1MUX, 16:1MUX, 32:1MUX Register-to-Register Performance (G 0.30) - No timing number changes.
			External Switching Characteristics (G 0.30) - No timing number changes.
			Internal Switching Characteristics (G 0.30) - t_{SUP_DSP} , t_{HP_DSP} , t_{SUO_DSP} , t_{HO_DSP} , t_{COI_DSP} , t_{COD_DSP} numbers have been updated.
			Family Timing Adders (G 0.30) - No timing number changes.
			sysCLOCK PLL Timing (G 0.30) - No timing number changes.
			sysCONFIG Port Timing Specifications (G 0.30) - No timing number changes.
			Master Clock (G 0.30) - No timing number changes.
			JTAG Port Timing Specification (G 0.30) - No timing number changes.
		Ordering Information	Added 208-PQFP lead-free part numbers.
March 2006	02.2	DC & Switching Characteristics	Added footnote 3. to V_{CCAUX} in the Recommended Operating Conditions table.
January 2007	02.3	Architecture	EBR Asynchronous Reset section added.
February 2007	02.4	Architecture	Updated EBR Asynchronous Reset section.
			Updated Maximum Number of Elements in a Block table - MAC value for x9 changed to 2.
May 2007	02.5	Architecture	Updated text in Ripple Mode section.
November 2007	02.6	DC & Switching Characteristics	Added JTAG Port Waveforms diagram.
			Updated t_{RST} timing information in the sysCLOCK PLL Timing table.
		Pinout Information	Added Thermal Management text section.
		Supplemental Information	Updated title list.
February 2008	02.7	DC & Switching Characteristics	Read/Write Mode (Normal) and Read/Write Mode with Input and Output Registers waveforms in the EBR Memory Timing Diagrams section have been updated.
September 2012	02.8	All	Updated document with new corporate logo.